

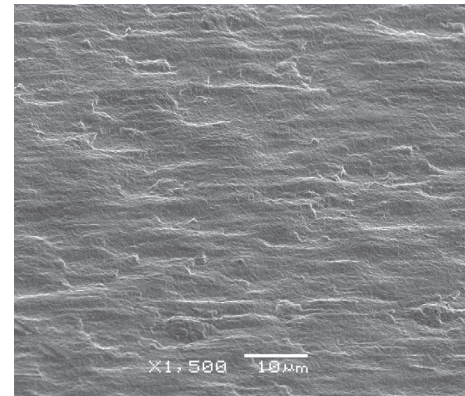
Low profile electrodeposited copper foil.

**Applications:**

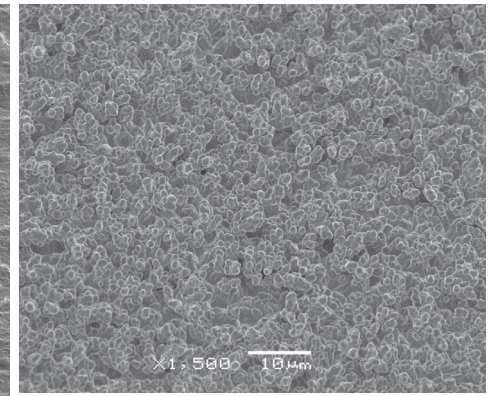
- PCB inner layers

**Features:**

- IPC Grade III
- Treatment on matte side of foil
- Excellent adhesion to a wide range of resin systems
- Arsenic free



Untreated Drum Side  
H oz. /18 µm (1500x)



Treated Matte Side  
H oz. /18 µm (1500x)

**Typical Values:**

Attribute		Unit	Value			Reference
Thickness Designation			H	1	2	IPC-4562, 1.2.5.1 Table 1-1; IPC-TM-650-2.2.12
Nominal Thickness		µm	18	35	70	
		oz.	1/2	1	2	
Area Weight		g/m <sup>2</sup>	152.5	305	610	
		g/254 in <sup>2</sup>	25	50	100	
		oz./ft <sup>2</sup>	0.5	1	2	
Roughness	Drum Side	µm	0.25			IPC-TM-650-2.2.17
		µ"	10			
	Matte Side	µm	5.1	6.3	10.2	
		µ"	200	250	400	
Tensile	Ambient	Kg/mm <sup>2</sup>	42.2	38.7	36.9	IPC-TM-650-2.4.18
		Kpsi	60	55	52.5	
	180°C	Kg/mm <sup>2</sup>	21			
		Kpsi	30			
Elongation	Ambient	%	8	15	20	
	180°C	%	8			
Peel Strength* (Matte/Treated Side)	Cond. B	Kg/cm	>0.71	> 0.80	> 0.89	IPC-TM-650-2.4.8
		Lbs/in	> 4.0	> 4.5	> 5.0	

\* Peel strength measured on 170°C Tg Epoxy

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